Infineon Technologies - SAF-XC888CM-8FFA 5V AC Datasheet

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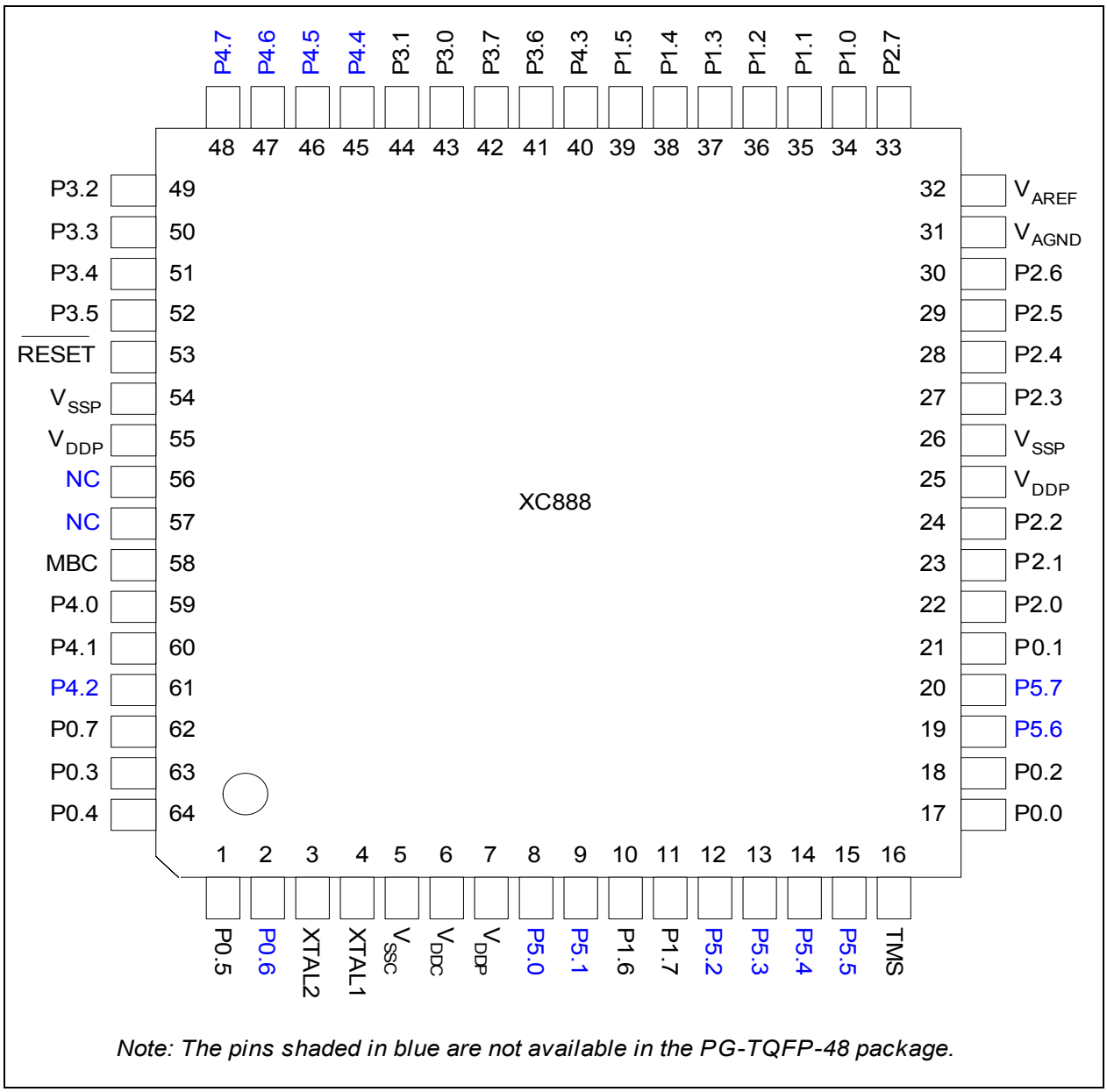
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	48
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	PG-TQFP-64
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc888cm-8ffa-5v-ac



Note: The pins shaded in blue are not available in the PG-TQFP-48 package.

Figure 5 XC888 Pin Configuration, PG-TQFP-64 Package (top view)

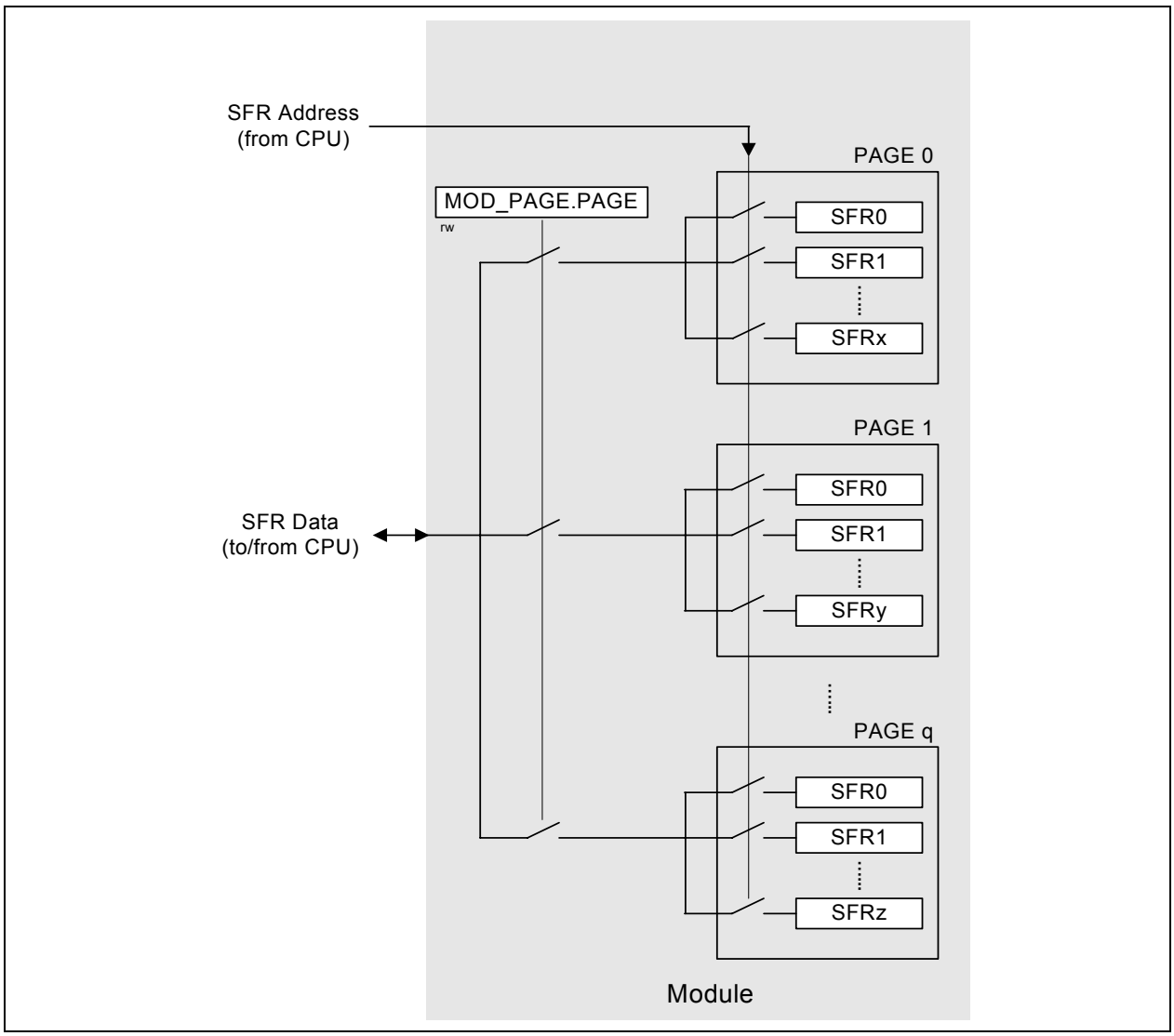


Figure 9 Address Extension by Paging

In order to access a register located in a page different from the actual one, the current page must be exited. This is done by reprogramming the bit field PAGE in the page register. Only then can the desired access be performed.

If an interrupt routine is initiated between the page register access and the module register access, and the interrupt needs to access a register located in another page, the current page setting can be saved, the new one programmed and the old page setting restored. This is possible with the storage fields STx (x = 0 - 3) for the save and restore action of the current page setting. By indicating which storage bit field should be used in parallel with the new page value, a single write operation can:

- Save the contents of PAGE in STx before overwriting with the new value
  (this is done in the beginning of the interrupt routine to save the current page setting and program the new page number); or

Table 9 WDT Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
BE_H	**WDTL** **Reset: 00_H** Watchdog Timer Register Low	Bit Field	WDT							
		Type	rh							
BF_H	**WDTH** **Reset: 00_H** Watchdog Timer Register High	Bit Field	WDT							
		Type	rh							

3.2.4.6 Port Registers

The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10 Port Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$B2_H$	**PORT_PAGE** **Reset: 00_H** Page Register	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rw		
RMAP = 0, PAGE 0										
80_H	**P0_DATA** **Reset: 00_H** P0 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
86_H	**P0_DIR** **Reset: 00_H** P0 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
90_H	**P1_DATA** **Reset: 00_H** P1 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
91_H	**P1_DIR** **Reset: 00_H** P1 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
92_H	**P5_DATA** **Reset: 00_H** P5 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
93_H	**P5_DIR** **Reset: 00_H** P5 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A0_H$	**P2_DATA** **Reset: 00_H** P2 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A1_H$	**P2_DIR** **Reset: 00_H** P2 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_DATA** **Reset: 00_H** P3 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B1_H$	**P3_DIR** **Reset: 00_H** P3 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C8_H$	**P4_DATA** **Reset: 00_H** P4 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C9_H$	**P4_DIR** **Reset: 00_H** P4 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$D3_H$	**ADC_RESR3H Reset: 00_H** Result Register 3 High	Bit Field	RESULT							
		Type	rh							
RMAP = 0, PAGE 3										
CA_H	**ADC_RESRA0L Reset: 00_H** Result Register 0, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CB_H	**ADC_RESRA0H Reset: 00_H** Result Register 0, View A High	Bit Field	RESULT							
		Type	rh							
CC_H	**ADC_RESRA1L Reset: 00_H** Result Register 1, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CD_H	**ADC_RESRA1H Reset: 00_H** Result Register 1, View A High	Bit Field	RESULT							
		Type	rh							
CE_H	**ADC_RESRA2L Reset: 00_H** Result Register 2, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CF_H	**ADC_RESRA2H Reset: 00_H** Result Register 2, View A High	Bit Field	RESULT							
		Type	rh							
$D2_H$	**ADC_RESRA3L Reset: 00_H** Result Register 3, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
$D3_H$	**ADC_RESRA3H Reset: 00_H** Result Register 3, View A High	Bit Field	RESULT							
		Type	rh							
RMAP = 0, PAGE 4										
CA_H	**ADC_RCR0 Reset: 00_H** Result Control Register 0	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CB_H	**ADC_RCR1 Reset: 00_H** Result Control Register 1	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CC_H	**ADC_RCR2 Reset: 00_H** Result Control Register 2	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CD_H	**ADC_RCR3 Reset: 00_H** Result Control Register 3	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CE_H	**ADC_VFCR Reset: 00_H** Valid Flag Clear Register	Bit Field	0				VFC3	VFC2	VFC1	VFC0
		Type	r				w	w	w	w
RMAP = 0, PAGE 5										
CA_H	**ADC_CHINFR Reset: 00_H** Channel Interrupt Flag Register	Bit Field	CHINF7	CHINF6	CHINF5	CHINF4	CHINF3	CHINF2	CHINF1	CHINF0
		Type	rh	rh	rh	rh	rh	rh	rh	rh
CB_H	**ADC_CHINCR Reset: 00_H** Channel Interrupt Clear Register	Bit Field	CHINC7	CHINC6	CHINC5	CHINC4	CHINC3	CHINC2	CHINC1	CHINC0
		Type	w	w	w	w	w	w	w	w

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
CC_H	**ADC_CHINSR Reset: 00_H** Channel Interrupt Set Register	Bit Field	CHINS 7	CHINS 6	CHINS 5	CHINS 4	CHINS 3	CHINS 2	CHINS 1	CHINS 0
		Type	w	w	w	w	w	w	w	w
CD_H	**ADC_CHINPR Reset: 00_H** Channel Interrupt Node Pointer Register	Bit Field	CHINP 7	CHINP 6	CHINP 5	CHINP 4	CHINP 3	CHINP 2	CHINP 1	CHINP 0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
CE_H	**ADC_EVINFR Reset: 00_H** Event Interrupt Flag Register	Bit Field	EVINF 7	EVINF 6	EVINF 5	EVINF 4	0		EVINF 1	EVINF 0
		Type	rh	rh	rh	rh	r		rh	rh
CF_H	**ADC_EVINCR Reset: 00_H** Event Interrupt Clear Flag Register	Bit Field	EVINC 7	EVINC 6	EVINC 5	EVINC 4	0		EVINC 1	EVINC 0
		Type	w	w	w	w	r		w	w
$D2_H$	**ADC_EVINSR Reset: 00_H** Event Interrupt Set Flag Register	Bit Field	EVINS 7	EVINS 6	EVINS 5	EVINS 4	0		EVINS 1	EVINS 0
		Type	w	w	w	w	r		w	w
$D3_H$	**ADC_EVINPR Reset: 00_H** Event Interrupt Node Pointer Register	Bit Field	EVINP 7	EVINP 6	EVINP 5	EVINP 4	0		EVINP 1	EVINP 0
		Type	rw	rw	rw	rw	r		rw	rw
RMAP = 0, PAGE 6										
CA_H	**ADC_CRCR1 Reset: 00_H** Conversion Request Control Register 1	Bit Field	CH7	CH6	CH5	CH4	0			
		Type	rwh	rwh	rwh	rwh	r			
CB_H	**ADC_CRPR1 Reset: 00_H** Conversion Request Pending Register 1	Bit Field	CHP7	CHP6	CHP5	CHP4	0			
		Type	rwh	rwh	rwh	rwh	r			
CC_H	**ADC_CRMR1 Reset: 00_H** Conversion Request Mode Register 1	Bit Field	Rsv	LDEV	CLRP ND	SCAN	ENSI	ENTR	0	ENGT
		Type	r	w	w	rw	rw	rw	r	rw
CD_H	**ADC_QMR0 Reset: 00_H** Queue Mode Register 0	Bit Field	CEV	TREV	FLUS H	CLRV	0	ENTR	0	ENGT
		Type	w	w	w	w	r	rw	r	rw
CE_H	**ADC_QSR0 Reset: 20_H** Queue Status Register 0	Bit Field	Rsv	0	EMPT Y	EV	0		FILL	
		Type	r	r	rh	rh	r		rh	
CF_H	**ADC_Q0R0 Reset: 00_H** Queue 0 Register 0	Bit Field	EXTR	ENSI	RF	V	0	REQCHNR		
		Type	rh	rh	rh	rh	r	rh		
$D2_H$	**ADC_QBUR0 Reset: 00_H** Queue Backup Register 0	Bit Field	EXTR	ENSI	RF	V	0	REQCHNR		
		Type	rh	rh	rh	rh	r	rh		
$D2_H$	**ADC_QINR0 Reset: 00_H** Queue Input Register 0	Bit Field	EXTR	ENSI	RF	0		REQCHNR		
		Type	w	w	w	r		w		

3.2.4.8 Timer 2 Registers

The Timer 2 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 12 T2 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$C0_H$	**T2_T2CON** **Reset: 00_H** Timer 2 Control Register	Bit Field	TF2	EXF2	0		EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$
		Type	rwh	rwh	r		rw	rwh	rw	rw
$C1_H$	**T2_T2MOD** **Reset: 00_H** Timer 2 Mode Register	Bit Field	T2REGS	T2RHEN	EDGESEL	PREN	T2PRE			DCEN
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C2_H$	**T2_RC2L** **Reset: 00_H** Timer 2 Reload/Capture Register Low	Bit Field	RC2							
		Type	rwh							
$C3_H$	**T2_RC2H** **Reset: 00_H** Timer 2 Reload/Capture Register High	Bit Field	RC2							
		Type	rwh							
$C4_H$	**T2_T2L** **Reset: 00_H** Timer 2 Register Low	Bit Field	THL2							
		Type	rwh							
$C5_H$	**T2_T2H** **Reset: 00_H** Timer 2 Register High	Bit Field	THL2							
		Type	rwh							

3.2.4.9 Timer 21 Registers

The Timer 21 SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 13 T21 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
$C0_H$	**T21_T2CON** **Reset: 00_H** Timer 2 Control Register	Bit Field	TF2	EXF2	0		EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$
		Type	rwh	rwh	r		rw	rwh	rw	rw
$C1_H$	**T21_T2MOD** **Reset: 00_H** Timer 2 Mode Register	Bit Field	T2REGS	T2RHEN	EDGESEL	PREN	T2PRE			DCEN
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C2_H$	**T21_RC2L** **Reset: 00_H** Timer 2 Reload/Capture Register Low	Bit Field	RC2							
		Type	rwh							
$C3_H$	**T21_RC2H** **Reset: 00_H** Timer 2 Reload/Capture Register High	Bit Field	RC2							
		Type	rwh							
$C4_H$	**T21_T2L** **Reset: 00_H** Timer 2 Register Low	Bit Field	THL2							
		Type	rwh							

3.3.3 Flash Programming Width

For the P-Flash banks, a programmed wordline (WL) must be erased before it can be reprogrammed as the Flash cells can only withstand one gate disturb. This means that the entire sector containing the WL must be erased since it is impossible to erase a single WL.

For the D-Flash bank, the same WL can be programmed twice before erasing is required as the Flash cells are able to withstand two gate disturbs. This means if the number of data bytes that needs to be written is smaller than the 32-byte minimum programming width, the user can opt to program this number of data bytes (x; where x can be any integer from 1 to 31) first and program the remaining bytes (32 - x) later. Hence, it is possible to program the same WL, for example, with 16 bytes of data two times (see **Figure 12**)

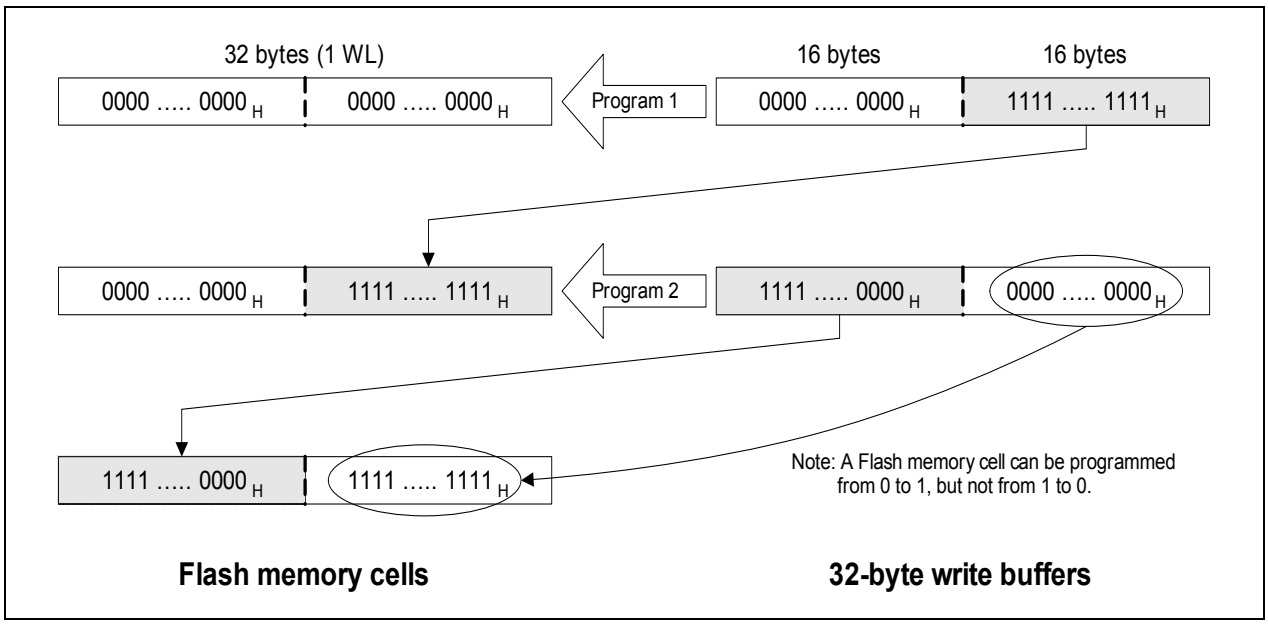


Figure 12 D-Flash Programming

Note: When programming a D-Flash WL the second time, the previously programmed Flash memory cells (whether 0s or 1s) should be reprogrammed with 0s to retain its original contents and to prevent "over-programming".

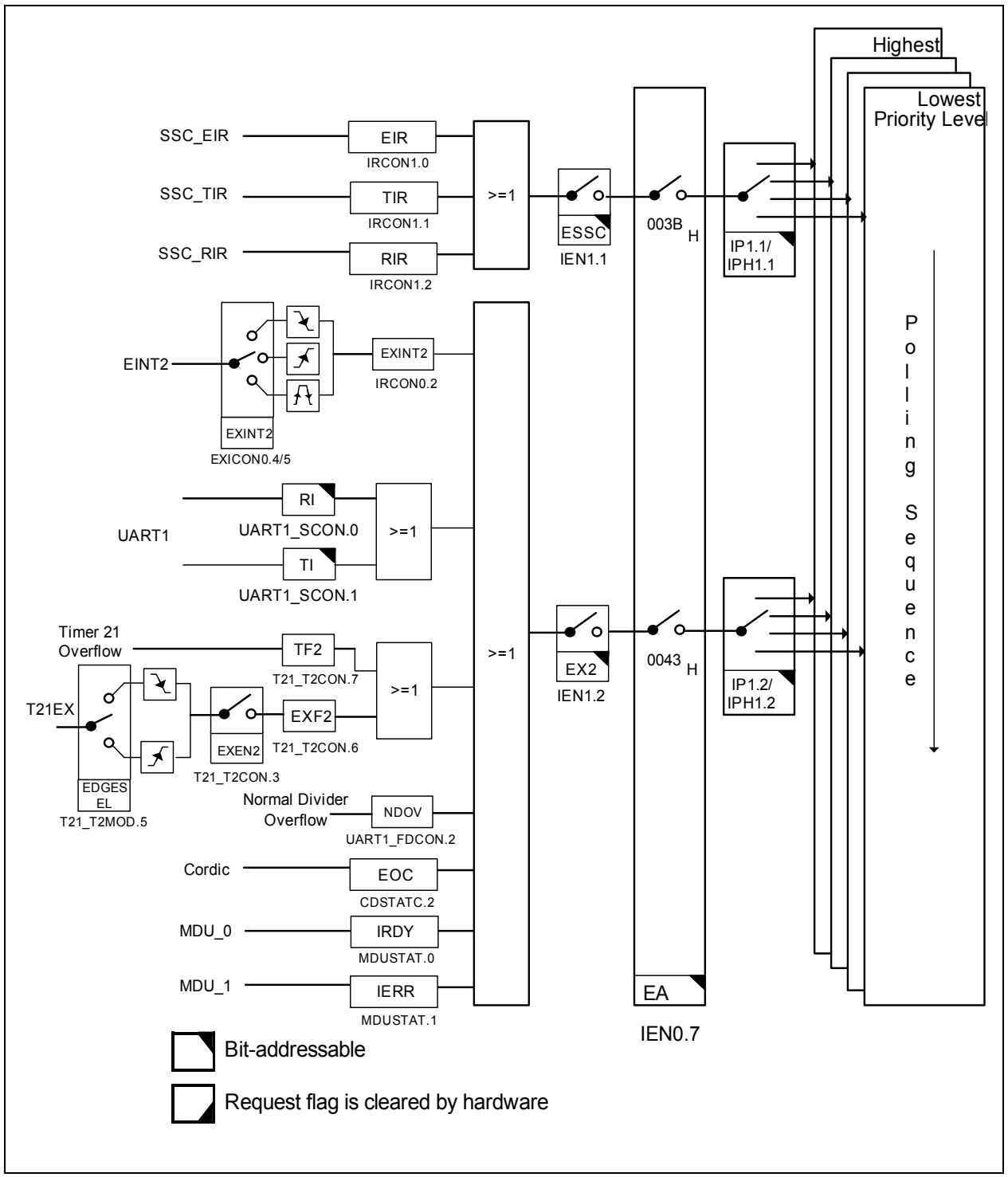


Figure 16 Interrupt Request Sources (Part 3)

If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert FNMIWDT) and the reset prewarning is entered. The prewarning period lasts for 30_H count, after which the system is reset (assert WDTRST).

The WDT has a “programmable window boundary” which disallows any refresh during the WDT’s count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from 0000_H to the value obtained from the concatenation of WDTWINB and 00_H.

After being serviced, the WDT continues counting up from the value (<WDTREL> * 2^8). The time period for an overflow of the WDT is programmable in two ways:

- The input frequency to the WDT can be selected to be either $f_{PCLK}/2$ or $f_{PCLK}/128$
- The reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT}, between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}} \quad (3.4)$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see **Figure 29**. This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB cannot be smaller than WDTREL.

3.12 CORDIC Coprocessor

The CORDIC Coprocessor provides CPU with hardware support for the solving of circular (trigonometric), linear (multiply-add, divide-add) and hyperbolic functions.

Features

- Modes of operation
  - Supports all CORDIC operating modes for solving circular (trigonometric), linear (multiply-add, divide-add) and hyperbolic functions
  - Integrated look-up tables (LUTs) for all operating modes
- Circular vectoring mode: Extended support for values of initial X and Y data up to full range of $[-2^{15},(2^{15}-1)]$ for solving angle and magnitude
- Circular rotation mode: Extended support for values of initial Z data up to full range of $[-2^{15},(2^{15}-1)]$, representing angles in the range $[-\pi,((2^{15}-1)/2^{15})\pi]$ for solving trigonometry
- Implementation-dependent operational frequency of up to 80 MHz
- Gated clock input to support disabling of module
- 16-bit accessible data width
  - 24-bit kernel data width plus 2 overflow bits for X and Y each
  - 20-bit kernel data width plus 1 overflow bit for Z
  - With KEEP bit to retain the last value in the kernel register for a new calculation
- 16 iterations per calculation: Approximately 41 clock-cycles or less, from set of start (ST) bit to set of end-of-calculation flag, excluding time taken for write and read access of data bytes.
- Twos complement data processing
  - Only exception: X result data with user selectable option for unsigned result
- X and Y data generally accepted as integer or rational number; X and Y must be of the same data form
- Entries of LUTs are 20-bit signed integers
  - Entries of atan and atanh LUTs are integer representations (S19) of angles with the scaling such that $[-2^{15},(2^{15}-1)]$ represents the range $[-\pi,((2^{15}-1)/2^{15})\pi]$
  - Accessible Z result data for circular and hyperbolic functions is integer in data form of S15
- Emulated LUT for linear function
  - Data form is 1 integer bit and 15-bit fractional part (1.15)
  - Accessible Z result data for linear function is rational number with fixed data form of S4.11 (signed 4Q16)
- Truncation Error
  - The result of a CORDIC calculation may return an approximation due to truncation of LSBs
  - Good accuracy of the CORDIC calculated result data, especially in circular mode
- Interrupt
  - On completion of a calculation

fractional divider) for generating a wide range of baud rates based on its input clock f_{PCLK}, see **Figure 30**.

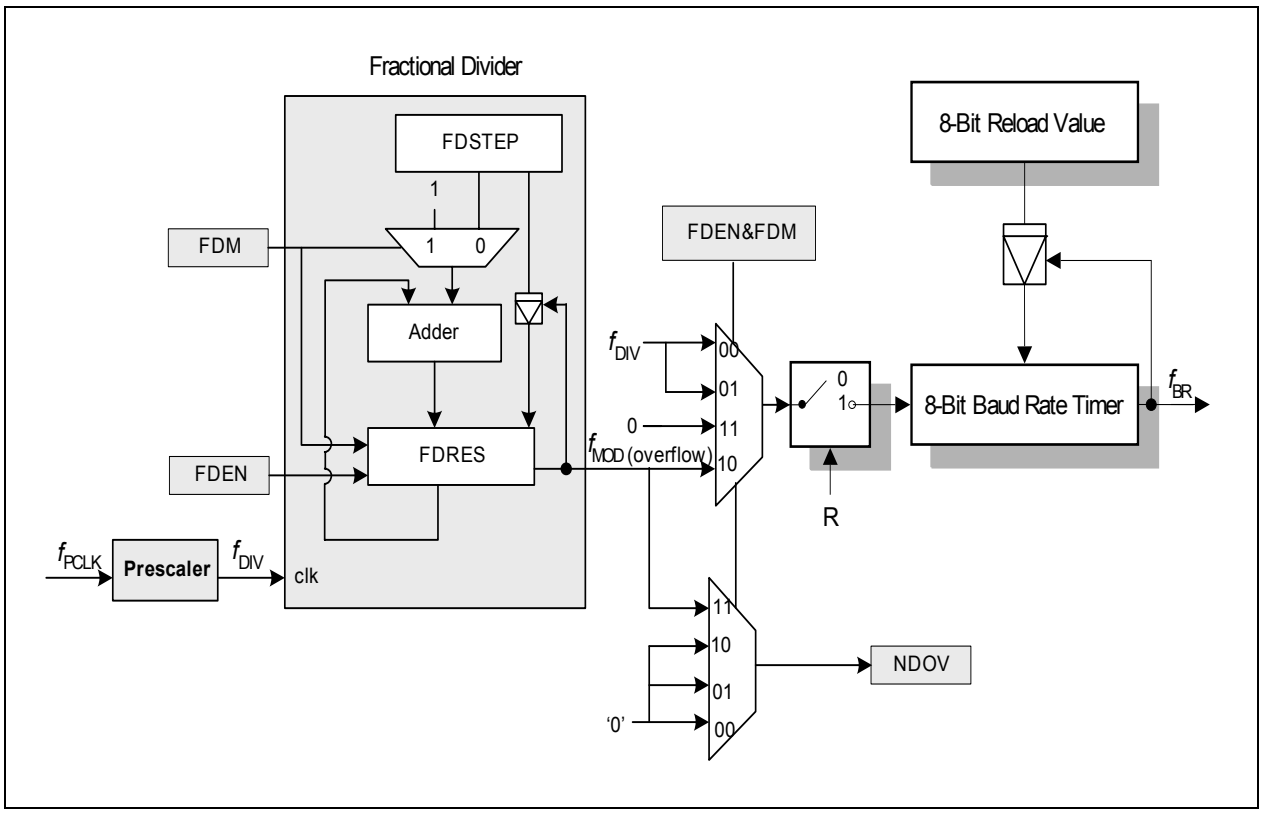


Figure 30 Baud-rate Generator Circuitry

The baud rate timer is a count-down timer and is clocked by either the output of the fractional divider (f_{MOD}) if the fractional divider is enabled (FDCON.FDEN = 1), or the output of the prescaler (f_{DIV}) if the fractional divider is disabled (FDEN = 0). For baud rate generation, the fractional divider must be configured to fractional divider mode (FDCON.FDM = 0). This allows the baud rate control run bit BCON.R to be used to start or stop the baud rate timer. At each timer underflow, the timer is reloaded with the 8-bit reload value in register BG and one clock pulse is generated for the serial channel.

Enabling the fractional divider in normal divider mode (FDEN = 1 and FDM = 1) stops the baud rate timer and nullifies the effect of bit BCON.R. See **Section 3.14**.

The baud rate (f_{BR}) value is dependent on the following parameters:

- Input clock f_{PCLK}
- Prescaling factor (2^{BRPRE}) defined by bit field BRPRE in register BCON
- Fractional divider (STEP/256) defined by register FDSTEP
  (to be considered only if fractional divider is enabled and operating in fractional divider mode)
- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

The following formulas calculate the final baud rate without and with the fractional divider respectively:

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \quad \text{where } 2^{BRPRE} \times (BR\_VALUE + 1) > 1 \tag{3.5}$$

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \times \frac{STEP}{256} \tag{3.6}$$

The maximum baud rate that can be generated is limited to $f_{PCLK}/32$. Hence, for a module clock of 24 MHz, the maximum achievable baud rate is 0.75 MBaud.

Standard LIN protocol can support a maximum baud rate of 20 kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20 kHz to 115.2 kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 30 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 24 MHz is used.

Table 30 Typical Baud rates for UART with Fractional Divider disabled

Baud rate	Prescaling Factor (2BRPRE)	Reload Value (BR_VALUE + 1)	Deviation Error
19.2 kBaud	1 (BRPRE=000_B)	78 ($4E_H$)	0.17 %
9600 Baud	1 (BRPRE=000_B)	156 ($9C_H$)	0.17 %
4800 Baud	2 (BRPRE=001_B)	156 ($9C_H$)	0.17 %
2400 Baud	4 (BRPRE=010_B)	156 ($9C_H$)	0.17 %

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 31** lists the resulting deviation errors from generating a baud rate of 115.2 kHz, using different module clock frequencies. The fractional divider is enabled (fractional divider mode) and the corresponding parameter settings are shown.

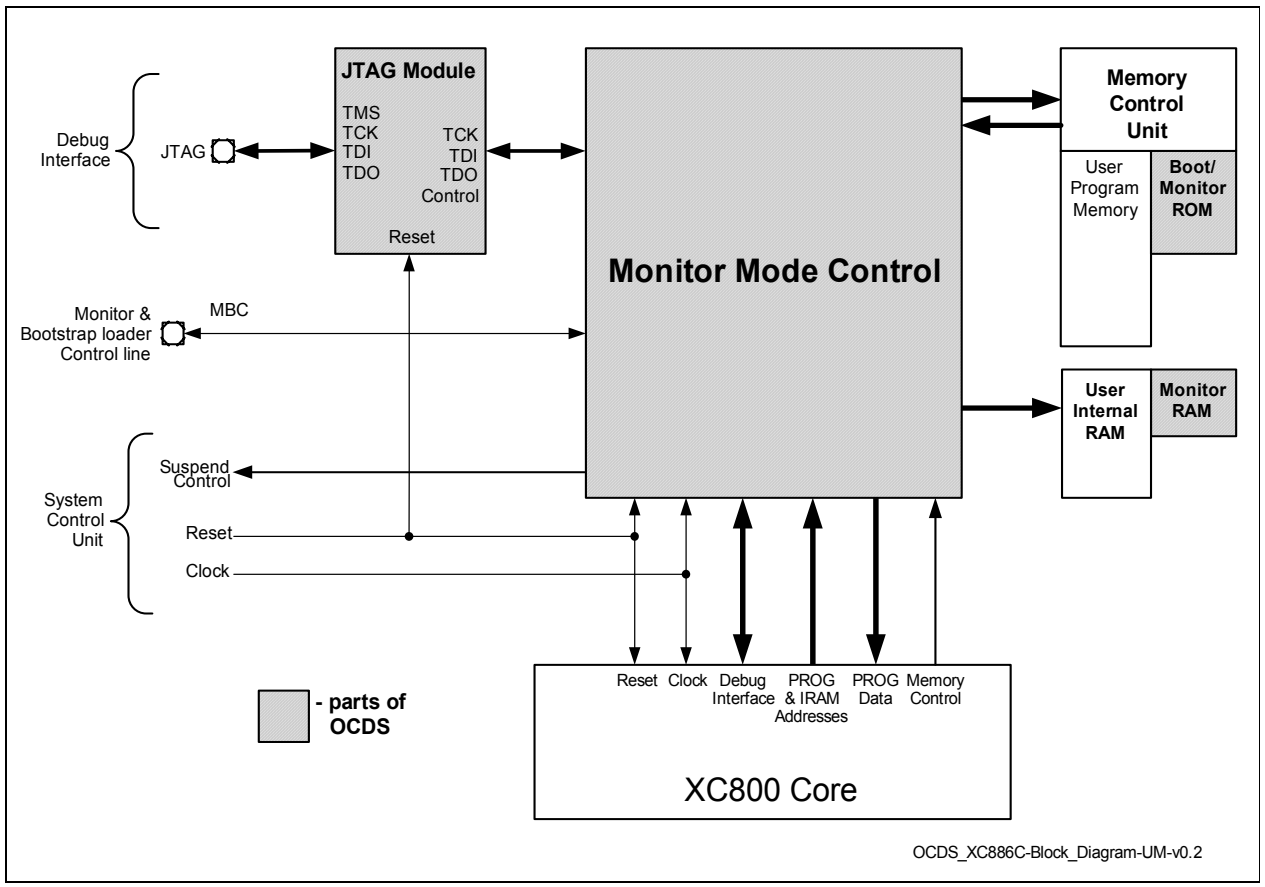


Figure 37 OCDS Block Diagram

3.22.1 JTAG ID Register

This is a read-only register located inside the JTAG module, and is used to recognize the device(s) connected to the JTAG interface. Its content is shifted out when INSTRUCTION register contains the IDCODE command (opcode 04_H), and the same is also true immediately after reset.

The JTAG ID register contents for the XC886/888 Flash devices are given in **Table 35**.

Table 35 JTAG ID Summary

Device Type	Device Name	JTAG ID
Flash	XC886/888*-8FF	$1012\ 0083_H$
	XC886/888*-6FF	$1012\ 5083_H$
ROM	XC886/888*-8RF	$1013\ C083_H$
	XC886/888*-6RF	$1013\ D083_H$

Note: The asterisk (*) above denotes all possible device configurations.

Table 36 Chip Identification Number (cont'd)

Product Variant	Chip Identification Number		
	AA-Step	AB-Step	AC-Step
XC886LM-6RFA 3V3	22411522_H	-	-
XC888LM-6RFA 3V3	22411523_H	-	-
XC886CM-8RFA 3V3	22480502_H	-	-
XC888CM-8RFA 3V3	22480503_H	-	-
XC886C-8RFA 3V3	22480542_H	-	-
XC888C-8RFA 3V3	22480543_H	-	-
XC886-8RFA 3V3	22480562_H	-	-
XC888-8RFA 3V3	22480563_H	-	-
XC886CM-6RFA 3V3	22491502_H	-	-
XC888CM-6RFA 3V3	22491503_H	-	-
XC886C-6RFA 3V3	22491542_H	-	-
XC888C-6RFA 3V3	22491543_H	-	-
XC886-6RFA 3V3	22491562_H	-	-
XC888-6RFA 3V3	22491563_H	-	-
XC886CLM-8RFA 5V	22800502_H	-	-
XC888CLM-8RFA 5V	22800503_H	-	-
XC886LM-8RFA 5V	22800522_H	-	-
XC888LM-8RFA 5V	22800523_H	-	-
XC886CLM-6RFA 5V	22811502_H	-	-
XC888CLM-6RFA 5V	22811503_H	-	-
XC886LM-6RFA 5V	22811522_H	-	-
XC888LM-6RFA 5V	22811523_H	-	-
XC886CM-8RFA 5V	22880502_H	-	-
XC888CM-8RFA 5V	22880503_H	-	-
XC886C-8RFA 5V	22880542_H	-	-
XC888C-8RFA 5V	22880543_H	-	-
XC886-8RFA 5V	22880562_H	-	-
XC888-8RFA 5V	22880563_H	-	-
XC886CM-6RFA 5V	22891502_H	-	-

4.1.2 Absolute Maximum Rating

Maximum ratings are the extreme limits to which the XC886/888 can be subjected to without permanent damage.

Table 4-1 Absolute Maximum Rating Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Ambient temperature	T_A	-40	125	°C	under bias
Storage temperature	T_{ST}	-65	150	°C	1)
Junction temperature	T_J	-40	150	°C	under bias1)
Voltage on power supply pin with respect to V_{SS}	V_{DDP}	-0.5	6	V	1)
Voltage on any pin with respect to V_{SS}	V_{IN}	-0.5	V_{DDP} + 0.5 or max. 6	V	whichever is lower1)
Input current on any pin during overload condition	I_{IN}	-10	10	mA	1)
Absolute sum of all input currents during overload condition	$\Sigma\|I_{IN}\|$	–	50	mA	1)

1) Not subjected to production test, verified by design/characterization.

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. During absolute maximum rating overload conditions ($V_{IN} > V_{DDP}$ or $V_{IN} < V_{SS}$) the voltage on V_{DDP} pin with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.

Table 38 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
Maximum current out of V_{SS}	I_{MVSS}	SR	–	120	mA	[3]
V_{DDP} = 3.3 V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 8 mA
			–	0.4	V	I_{OL} = 2.5 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -8 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -2.5 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on RESET pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode
Input high voltage on RESET pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis	HYS	CC	0.03 × V_{DDP}	–	V	CMOS Mode[1]
Input Hysteresis on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	[1]
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	

4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins (V_{SS}) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

Table 40 ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)

Parameter	Symbol		Limit Values			Unit	Test Conditions/ Remarks
			min.	typ .	max.		
Analog reference voltage	V_{AREF}	SR	V_{AGND} + 1	V_{DDP}	V_{DDP} + 0.05	V	[1]
Analog reference ground	V_{AGND}	SR	V_{SS} - 0.05	V_{SS}	V_{AREF} - 1	V	[1]
Analog input voltage range	V_{AIN}	SR	V_{AGND}	–	V_{AREF}	V	
ADC clocks	f_{ADC}		–	24	25.8	MHz	module clock[1]
	f_{ADCI}		–	–	10	MHz	internal analog clock[1] See **Figure 35**
Sample time	t_S	CC	(2 + INPCR0.STC) × t_{ADCI}			µs	[1]
Conversion time	t_C	CC	See **Section 4.2.3.1**			µs	[1]
Total unadjusted error	|TUE|	CC	–	–	1	LSB	8-bit conversion[2]
			–	–	2	LSB	10-bit conversion[2]
Differential Nonlinearity	$\|EA_{DNL}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Integral Nonlinearity	$\|EA_{INL}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Offset	$\|EA_{OFF}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Gain	$\|EA_{GAIN}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Overload current coupling factor for analog inputs	K_{OVA}	CC	–	–	1.0 x 10^{-4}	–	$I_{OV} > 0$[1][3]
			–	–	1.5 x 10^{-3}	–	$I_{OV} < 0$[1][3]

4.2.4 Power Supply Current

Table 41, **Table 42**, **Table 43** and **Table 44** provide the characteristics of the power supply current in the XC886/888.

Table 41 Power Supply Current Parameters (Operating Conditions apply; V_{DDP} = 5V range)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
V_{DDP} = 5V Range					
Active Mode	I_{DDP}	27.2	32.8	mA	Flash Device[3]
		24.3	29.8	mA	ROM Device[3]
Idle Mode	I_{DDP}	21.1	25.3	mA	Flash Device[4]
		18.2	21.6	mA	ROM Device[4]
Active Mode with slow-down enabled	I_{DDP}	14.1	17.0	mA	Flash Device[5]
		11.9	14.3	mA	ROM Device[5]
Idle Mode with slow-down enabled	I_{DDP}	11.7	15.0	mA	Flash Device[6]
		9.7	11.9	mA	ROM Device[6]

1) The typical I_{DDP} values are periodically measured at T_A = + 25 °C and V_{DDP} = 5.0 V.

2) The maximum I_{DDP} values are measured under worst case conditions (T_A = + 125 °C and V_{DDP} = 5.5 V).

3) I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz(set by on-chip oscillator of 9.6 MHz and NDIV in PLL_CON to 1001_B), $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

4) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

5) I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 8 MHz by setting CLKREL in CMCON to 0110_B, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

6) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 8 MHz by setting CLKREL in CMCON to 0110_B, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

Table 43 Power Supply Current Parameters (Operating Conditions apply; V_{DDP} = 3.3V range)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
V_{DDP} = 3.3V Range					
Active Mode	I_{DDP}	25.6	31.0	mA	Flash Device[3]
		23.4	28.6	mA	ROM Device[3]
Idle Mode	I_{DDP}	19.9	24.7	mA	Flash Device[4]
		17.5	20.7	mA	ROM Device[4]
Active Mode with slow-down enabled	I_{DDP}	13.3	16.2	mA	Flash Device[5]
		11.5	13.7	mA	ROM Device[5]
Idle Mode with slow-down enabled	I_{DDP}	11.1	14.4	mA	Flash Device[6]
		9.3	11.4	mA	ROM Device[6]

1) The typical I_{DDP} values are periodically measured at T_A = + 25 °C and V_{DDP} = 3.3 V.

2) The maximum I_{DDP} values are measured under worst case conditions (T_A = + 125 °C and V_{DDP} = 3.6 V).

3) I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz(set by on-chip oscillator of 9.6 MHz and NDIV in PLL_CON to 1001_B), $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

4) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

5) I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 8 MHz by setting CLKREL in CMCON to 0110_B, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

6) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 8 MHz by setting CLKREL in CMCON to 0110_B,, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

4.3.2 Output Rise/Fall Times

Table 45 provides the characteristics of the output rise/fall times in the XC886/888.

Table 45 Output Rise/Fall Times Parameters (Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Conditions
		min.	max.		
V_{DDP} = 5V Range					
Rise/fall times	t_R, t_F	–	10	ns	20 pF.[1)2)3)]
V_{DDP} = 3.3V Range					
Rise/fall times	t_R, t_F	–	10	ns	20 pF.[1)2)4)]

1) Rise/Fall time measurements are taken with 10% - 90% of pad supply.
2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.
3) Additional rise/fall time valid for C_L = 20pF - 100pF @ 0.125 ns/pF.
4) Additional rise/fall time valid for C_L = 20pF - 100pF @ 0.225 ns/pF.

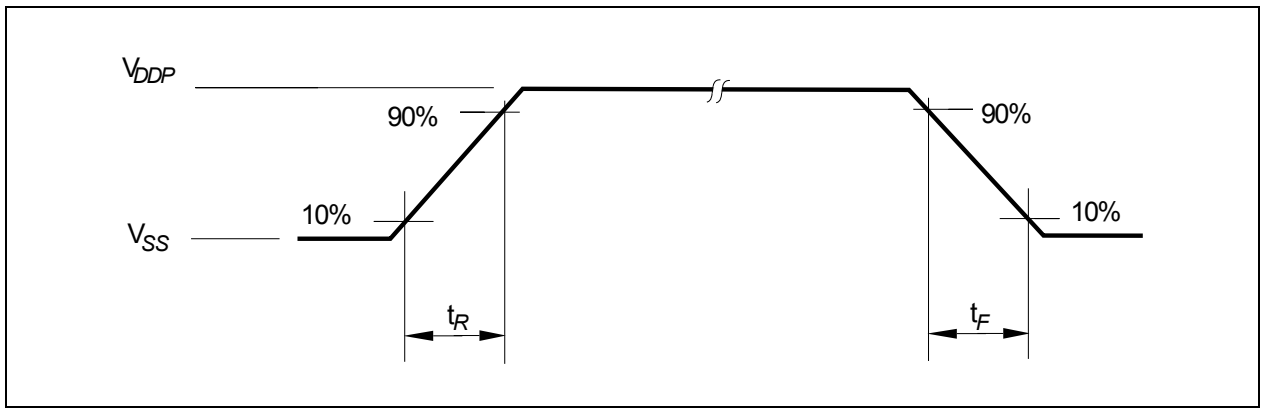


Figure 43 Rise/Fall Times Parameters